

## **650V N-Channel Power MOSFET**

#### **General Description**

BCT16N65 uses advanced technology to provide low R<sub>DS(on)</sub>, low gate charge and fast switching characteristics. This device is suitable for power applications.

#### **Features**

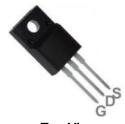
Low R<sub>DS(on)</sub> Low FOM Extremely low switching loss Good stability and uniformity

### **Applications**

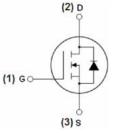
Consumer electronics power supply LCD/LED/PDP
Portable digital power management PFC

BV <sub>DSS</sub>	650	V		
ID	16	Α		
R <sub>DS(on),typical@10V</sub>	0.49	Ω		
V <sub>GS(th),typical</sub>	3	V		
Package	TO-220F			

#### **TO-220F**



**Top View** 



**Schematic Diagram** 

## **Ordering Information**

Part Number	Package	Form	Minimum Order Quantity
BCT16N65	TO-220F	Tube	1000

### **Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	650	V
Gate-Source Voltage	$V_{GS}$	±30	V
Drain Current-Continuous(Note 1)	ID	16	Α
Drain Current-Pulsed <sup>(Note 2)</sup>	Ірм	64	Α
Power Dissipation <sup>(Note 3)</sup>	P <sub>D</sub>	70	W
Single Pulsed-Avalanche Energy(Note 4)	Eas	800	mJ
Operation and Storage Junction Temperature	$T_{J,}T_{STG}$	-55 to 150	°C

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>0</sub> JC	1.79	°C/W
Thermal Resistance, Junction-to-Ambient (Note 5)	Reja	62	°C/W

# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test condition
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	650			V	$V_{GS} = 0V, I_D = 250\mu A$
Gate Threshold Voltage	$V_{\text{GS(th)}}$	2	3	4	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Drain-Source On-State Resistance	R <sub>DS(on)</sub>		0.49	0.55	Ω	$V_{GS} = 10V, I_D = 8A$
Gate-Source Leakage Current	I <sub>GSS</sub>			100	nA	V <sub>GS</sub> = 30V
				-100	nA	V <sub>GS</sub> = -30V
Drain-Source Leakage Current	I <sub>DSS</sub>			1	μΑ	V <sub>DS</sub> = 650V,V <sub>GS</sub> = 0V

## **Dynamic Characteristics**

Input Capacitance	Ciss	2	540	pF	$V_{GS} = 0V$ ,
Output Capacitance	Coss	2	18	pF	$V_{DS} = 25V$ ,
Reverse Transfer Capacitance	Crss		18	pF	f = 1MHz
Turn-On Delay Time	t <sub>d(on)</sub>	;	30	ns	I <sub>D</sub> = 8A,
Turn-On Rise Time	t <sub>r</sub>		70	ns	V <sub>GS</sub> = 10V,
Turn-Off Delay Time	t <sub>d(off)</sub>	1	45	ns	$V_{DS} = 325V$ ,
Turn-Off Fall Time	t <sub>f</sub>		74	ns	$R_G = 3\Omega$

## **Gate Charge Characteristics**

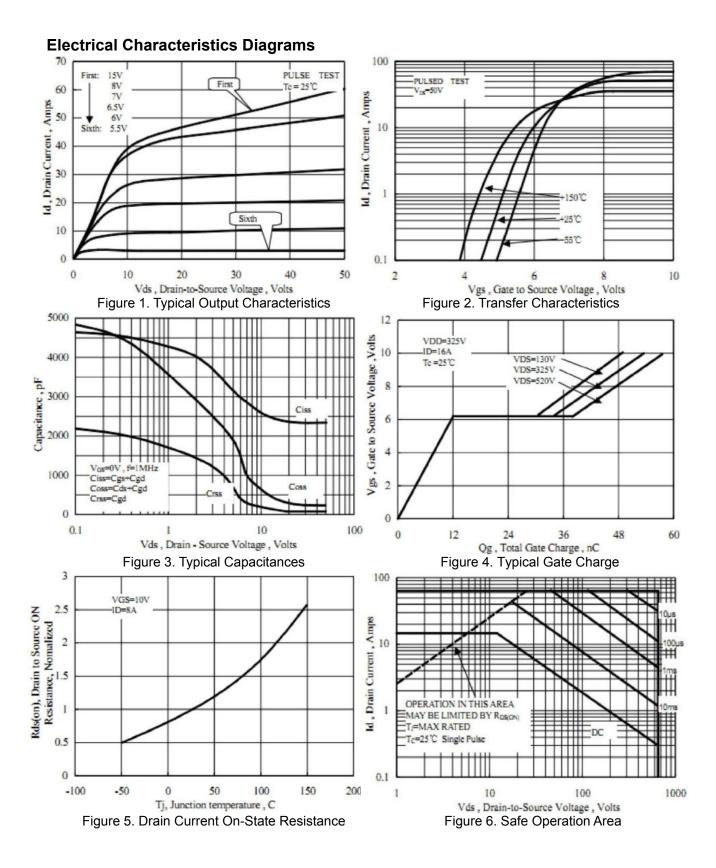
Total Gate Charge	Qg	54	nC	I <sub>D</sub> = 8A,
Gate-Source Charge	$Q_{gs}$	10	nC	V <sub>DS</sub> = 325V,
Gate-Drain Charge	$Q_{gd}$	21	nC	V <sub>GS</sub> = 10V

## **Body Diode Characteristics**

Body Diode Forward Current	Is		16	Α	$V_{GS} < V_{th}$
Diode Forward Voltage	V <sub>SD</sub>		1.5	V	I <sub>S</sub> =16A, V <sub>GS</sub> = 0V
Reverse Recovery Time	t <sub>rr</sub>	410		ns	I <sub>S</sub> = 16A, V <sub>GS</sub> = 0V
Reverse Recovery Charge	Qrr	3.5		μC	di/dt = 100A/µs

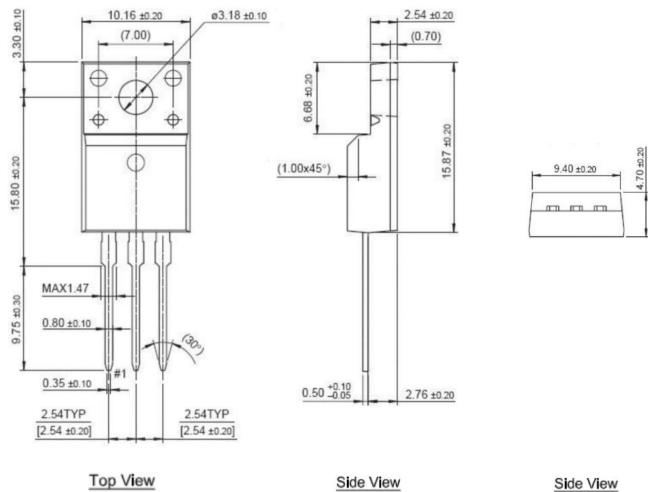
#### **Notes**

- 1. Calculated continuous current based on maximum allowable junction temperature.
- 2. Repetitive rating, pulse width limited by maximum junction temperature.
- 3.  $P_D$  is based on maximum junction temperature, using junction-to-case thermal resistance.
- 4.  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , L = 10mH, Starting  $T_J$  = 25 $^{\circ}$ C.
- 5. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25°C.



# **Package Outline Dimensions**





Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO-220F	50	20	1000	5	5000